AREA OF INTEREST

The Symposium invites papers in the following areas relevant to the Symposium theme, but papers in other related areas will also be considered:

- Abrasive machining
- Abrasive jet machining
- Advanced cutting technology
- Beam-aided processing
- Brittle material machining
- CMP and semiconductor wafer processing
- Coolants and cooling
- Design, fabrication and analysis of devices for the applications of abrasive technologies
- Eco-machining
- EDM, ultrasonic machining, and laser machining
- Finishing, lapping, and polishing
- Glass molding and related topics
- Grinding wheel and abrasive grain technologies
- High speed and high-efficiency machining
- In-process measurement and monitoring, metrology
- Machine tools and systems, tooling processing
- Micro/nano-machining
- Surface integrity and materials characterization
- Tribology in manufacturing
- Truing, dressing, and ELID

IMPORTANT DATES IN 2014

March 1	Abstract submission
March 31	Full paper submission
April 30	Notification of paper acceptance
May 20	Submission of final paper
June 5	Payment of early registration fee (including student registration fee)
Sept 22	Conference registration and reception
Sept 23-24	Technical sessions
Sept 25	Technical visit

SUBMISSION GUIDELINE

- For the account registration, abstract (including paper title and general Information of authors) should be submitted prior to full paper submission via the ISAAT2014 webpage: **http:// www.scoop-japan.com/kaigi/isaat2014/**
- Full papers must be written in English, and its length must be **from 4 to 6 proceedings pages**.
- Each paper must be formatted and submitted according to the **Instructions for Authors** available in the conference webpage.

PAPER PRESENTATION & PUBLICATION

All papers will be peer reviewed. Accepted papers MUST be presented in oral or poster session. Each delegate may present up to two papers (a publication fee will be charged for the second paper). The conference proceedings will be published as special volumes in an EI indexed international journal: **Advanced Materials Research**.

ACCOMMODATION

Information of hotels will be available on the conference webpage.

TRAVEL INFORMATION

Information on local travel will be available on the conference webpage.

SYMPOSIUM SECRETARIAT

ISAAT2014 Secretariat: Prof. H. Sakamoto

Email: **ISAAT2014@me.sophia.ac.jp**

Tel: +81 3 3238 3405, Fax: +81 3 3238 3405

For conference details, updates and downloadable documents, visit the conference website at

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Call for Papers

ISAAT 2014

The 17th International Symposium on Advances in Abrasive Technology

22-25 September 2014

Courtyard by Marriott King Kamehameha's
Kona Beach Hotel
Hawaii Island, Hawaii, USA

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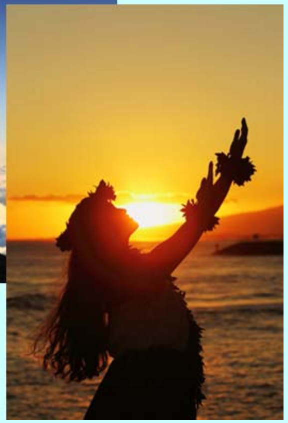

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ISAAT2014

September 22- 25, 2014

HISTORY & SCOPE

The International Symposium on Advances in Abrasive Technology (ISAAT) was first held in Sydney, Australia in 1997. Since 2002, JSAT and ICAT have been jointly organizing this exciting annual event for this community and the symposia have been successfully held in Hong Kong, UK, Turkey, Russia, US, Japan, Australia, Taiwan, Germany, Singapore and China. An emphasis of the ISAAT series is to bring together both academic researchers and industrial practitioners from around the world for the interchange of the latest developments and applications in abrasive technologies. The ISAAT2014 at Imiloa Astronomy Center Hawaii will continue to promote the discipline development and research collaboration, and to foster the growth of young engineers and researchers in the field.

REGISTRATION

Full registration:	JPY70,000 (by June 5, 2014)
Student registration:	JPY 50,000 (by June 5, 2014)
Late registration: (after June 6, 2014)	JPY 80,000 (Full registration) JPY70,000 (Student registration)

A full registration covers the costs of conference proceedings, welcoming reception, banquet, morning and afternoon refreshments, attendance to all technical sessions, and lunches. A student registration does not include the cost of banquet.

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